

ABSTRACT OF THE DISCLOSURE

Provided are a UV-curable pressure-sensitive adhesive composition comprising a photoinitiator which has a molar absorptivity at 365 nm of at least 1,000 mol<sup>-1</sup>·cm<sup>-1</sup> and the maximum absorption wavelength of at least 420 nm on a long wavelength side; and an adhesive sheet having a layer of the composition disposed over a photo-transmitting base film. The pressure-sensitive adhesive sheet according to the invention can be cured even by exposure to ultraviolet rays at a low intensity or for short time so that it can contribute to energy saving and productivity improvement as a sheet for processing, fixation or surface protection of a semiconductor wafer.